

Title (en)  
PARTIALLY PATTERNED LEAD FRAMES AND METHODS OF MAKING AND USING THE SAME IN SEMICONDUCTOR PACKAGING

Title (de)  
TEILWEISE STRUKTURIERTE ANSCHLUSSKÄMME UND VERFAHREN ZUR HERSTELLUNG UND VERWENDUNG DIESER BEI DER HALBLEITERKAPSELUNG

Title (fr)  
CADRES DE MONTAGE PARTIELLEMENT STRUCTURES ET PROCEDES DE PRODUCTION ET D'UTILISATION DE CES DERNIERS DANS LE CONDITIONNEMENT DE SEMI-CONDUCTEURS

Publication  
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Application  
**EP 03733901 A 20030428**

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Abstract (en)  
[origin: WO03103038A1] A method of making a lead frame and a partially patterned lead frame package with near-chip scale packaging (CSP) lead- counts is disclosed. This is accomplished by performing a major portion of the manufacturing process steps with a partially patterned strip of metal (100) formed into a web-like lead frame on one side. The bottom side of the metal lead frame is patterned to isolate the chip-pad and the wire bond contacts (113) only after the front side, including the chip (140) and wires (160), is hermetically sealed. The resultant package being electrically isolated enables strip testing and reliable singulation without having to cut into any additional metal.

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IPC 8 full level  
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CPC (source: EP KR)  
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